

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT8129922

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
HUILONG ZHU	08/22/2023
XIAOGEN YIN	08/22/2023
CHEN LI	08/22/2023
ANYAN DU	08/22/2023
YONGKUI ZHANG	08/22/2023
RECEIVING PARTY DATA	
Name:	THE INSTITUTE OF MICROELECTRONICS, CHINESE ACADEMY OF SCIENCES
Street Address:	NO. 3 BEITUCHENG WEST ROAD, CHAOYANG DISTRICT
City:	BEIJING
State/Country:	CHINA
Postal Code:	100029
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17891025
CORRESPONDENCE DATA	
Fax Number:	(206)757-7779
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	2066223150
Email:	patentdocket@dwt.com, tessalarson@dwt.com
Correspondent Name:	DAVIS WRIGHT TREMAINE LLP
Address Line 1:	920 FIFTH AVENUE
Address Line 2:	SUITE 3300
Address Line 4:	SEATTLE, WASHINGTON 98104-1610
ATTORNEY DOCKET NUMBER:	0090416-019US1
NAME OF SUBMITTER:	TESSA LARSON
SIGNATURE:	/Tessa Larson/
DATE SIGNED:	08/23/2023
Total Attachments: 3	

source=2023-08-23 FP220217US (0090416-019US1) Assignment (CIP)#page1.tif

source=2023-08-23 FP220217US (0090416-019US1) Assignment (CIP)#page2.tif

source=2023-08-23 FP220217US (0090416-019US1) Assignment (CIP)#page3.tif

ASSIGNMENT


WHEREAS, we, **Huilong ZHU**, having a mailing address of 93 Autumn Drive, Poughkeepsie, New York 12603, **Xiaogen YIN**, having a mailing address of No. 3 Beitucheng West Road, Chaoyang District, Beijing 100029 China, **Chen LI**, having a mailing address of No. 3 Beitucheng West Road, Chaoyang District, Beijing 100029 China, **Anyan DU**, having a mailing address of No. 3 Beitucheng West Road, Chaoyang District, Beijing 100029 China, and **Yongkui ZHANG**, having a mailing address of No. 3 Beitucheng West Road, Chaoyang District, Beijing 100029 China (hereinafter referred to as “ASSIGNORS”), respectively, are the joint inventors of an invention entitled “HIGH-PRECISION ETCHING METHOD” as described and claimed in U.S. Patent Application No. 17/891,025, filed August 18, 2022;

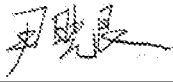
WHEREAS, **The Institute Of Microelectronics, Chinese Academy Of Sciences** (hereinafter referred to as “ASSIGNEE”), a corporation of China, having a mailing address of No. 3 Beitucheng West Road, Chaoyang District, Beijing 100029 China, is desirous of acquiring the entire right, title and interest in and to said invention, said application, and any and all letters patent that may be granted therefor in the United States and foreign countries;


NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNORS hereby sell, assign and transfer unto said ASSIGNEE, the entire right, title and interest in and to said invention, said application and any and all letters patent which may be granted for said invention in the United States of America and its territorial possessions and in any and all foreign countries, and in any and all divisions, reissues and continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEE and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty or otherwise, said invention, application and all letters patent on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns for their use and benefit and of their successors and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNORS had this assignment, transfer and sale not been made. ASSIGNORS hereby authorize and request the Commissioner of Patents and Trademarks to issue all letters patent on said invention to ASSIGNEE. Assignors agree to execute all instruments and documents required for the making and prosecution of applications for

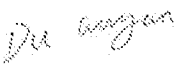
United States and foreign letters patent on said invention, for litigation regarding said letters patent, or for the purpose of protecting title to said invention or letters patent therefor.

Inventors:

Signature:  Date 08/22/2023
 Full Name: **Huilong ZHU**
 Mailing address: 93 Autumn Dr. Poughkeepsie, New York 12603 USA

Signature:  Date 08/22/2023
 Full Name: **Xiaogen YIN**
 Mailing address: No. 3 Beitucheng West Road, Chaoyang District, Beijing 100029 CHINA

Signature:  Date 08/22/2023
 Full Name: **Chen LI**
 Mailing address: No. 3 Beitucheng West Road, Chaoyang District, Beijing 100029 CHINA

Signature:  Date 08/22/2023
 Full Name: **Anyan DU**
 Mailing address: No. 3 Beitucheng West Road, Chaoyang District, Beijing 100029 CHINA

Signature: Yongkui ZHANG Date 08/22/2023
Full Name: **Yongkui ZHANG**
Mailing address: No. 3 Beitucheng West Road, Chaoyang District, Beijing 100029 CHINA
